



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20170927001
Qualify New Assembly Material set for Selected Device(s)
Change Notification / Sample Request

Date: October 03, 2017
To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

20170927001
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
ISO3082DWR	null
ISO3086DWR	null
ISO7220CD	null
ISO7240ADW	null
ISO1176DW	null
ISO7240CDW	null
ISO7242MDW	null
ISO3086DW	null
ISO721MD	null
ISO721MDR	null
ISO7221BDR	null
ISO722MD	null
ISO7240MDW	null
ISO7240MDWR	null
ISO7241ADW	null
ISO7241CDWR	null
ISO7242ADW	null
ISO7242CDWR	null
ISO15DWR	null
ISO721D	null
ISO3088DWR	null
ISO7240CDWR	null
ISO7240ADWR	null
ISO3080DWR	null
ISO7241CDW	null
ISO7242ADWR	null
ISO7242CDW	null
ISO1176DWR	null
ISO7220CDR	null
ISO7221CDR	null
MPD23782D	null
ISO7240CFDW	null
ISO3082DW	null
ISO7220MD	null
ISO7221MD	null
ISO7241MDW	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20170927001		PCN Date:	Oct. 3, 2017										
Title:	Qualify New Assembly Material set for Selected Device(s)													
Customer Contact:	PCN Manager		Dept:	Quality Services										
Proposed 1st Ship Date:	Apr 01, 2018		Estimated Sample Availability:	Date provided at sample request										
Change Type:														
☐	Assembly Site	☐	Design	☐	Wafer Bump Site									
☒	Assembly Process	☐	Data Sheet	☐	Wafer Bump Material									
☒	Assembly Materials	☐	Part number change	☐	Wafer Bump Process									
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site									
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials									
		☐		☐	Wafer Fab Process									
PCN Details														
Description of Change:														
Texas Instruments is pleased to announce the qualification of new assembly material set for devices listed in "Product affected" section below. Devices will remain in current assembly facility and piece part changes as follows: <table border="1" style="margin-left: auto; margin-right: auto;"> <thead> <tr> <th>Material</th> <th>Current</th> <th>Proposed</th> </tr> </thead> <tbody> <tr> <td>Mount compound</td> <td>4042500, 4208458</td> <td>4211470</td> </tr> <tr> <td>Mold compound</td> <td>4205694</td> <td>4209640</td> </tr> </tbody> </table>						Material	Current	Proposed	Mount compound	4042500, 4208458	4211470	Mold compound	4205694	4209640
Material	Current	Proposed												
Mount compound	4042500, 4208458	4211470												
Mold compound	4205694	4209640												
Reason for Change:														
Continuity of supply.														
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):														
None.														
Anticipated impact on Material Declaration														
☐	No Impact to the Material Declaration	☒	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI Eco-Info website . There is no impact to the material meeting current regulatory compliance requirements with this PCN change.											
Changes to product identification resulting from this PCN:														
None.														
Product Affected:														

ISO1176DW	ISO721MD	ISO7221MDRG4	ISO7240CDWR
ISO1176DWG4	ISO721MDG4	ISO722D	ISO7240CDWRG4
ISO1176DWR	ISO721MDR	ISO722DG4	ISO7240CFDW
ISO1176DWRG4	ISO721MDRG4	ISO722DR	ISO7240CFDWG4
ISO15DW	ISO7220AD	ISO722DRG4	ISO7240CFDWR
ISO15DWG4	ISO7220ADG4	ISO722MD	ISO7240MDW
ISO15DWR	ISO7220ADR	ISO722MDR	ISO7240MDWG4
ISO15DWRG4	ISO7220ADRG4	ISO722MDRG4	ISO7240MDWR
ISO15MDW	ISO7220BD	ISO7230ADW	ISO7240MDWRG4
ISO15MDWR	ISO7220BDG4	ISO7230ADWG4	ISO7241ADW
ISO3080DW	ISO7220BDR	ISO7230ADWR	ISO7241ADWG4
ISO3080DWG4	ISO7220BDRG4	ISO7230CDW	ISO7241ADWR
ISO3080DWR	ISO7220CD	ISO7230CDWG4	ISO7241ADWRG4
ISO3080DWRG4	ISO7220CDG4	ISO7230CDWR	ISO7241CDW
ISO3082DW	ISO7220CDR	ISO7230MDW	ISO7241CDWG4
ISO3082DWG4	ISO7220CDRG4	ISO7230MDWG4	ISO7241CDWR
ISO3082DWR	ISO7220MD	ISO7230MDWR	ISO7241CDWRG4
ISO3082DWRG4	ISO7220MDG4	ISO7231ADW	ISO7241MDW
ISO3086DW	ISO7220MDR	ISO7231ADWG4	ISO7241MDWG4
ISO3086DWG4	ISO7220MDRG4	ISO7231ADWR	ISO7241MDWR
ISO3086DWR	ISO7221AD	ISO7231ADWRG4	ISO7241MDWRG4
ISO3088DW	ISO7221ADG4	ISO7231CDW	ISO7242ADW
ISO3088DWG4	ISO7221ADR	ISO7231CDWG4	ISO7242ADWG4
ISO3088DWR	ISO7221ADRG4	ISO7231CDWR	ISO7242ADWR
ISO3088DWRG4	ISO7221BD	ISO7231CDWRG4	ISO7242ADWRG4
ISO35DW	ISO7221BDG4	ISO7231MDW	ISO7242CDW
ISO35DWG4	ISO7221BDR	ISO7231MDWG4	ISO7242CDWG4
ISO35DWR	ISO7221BDRG4	ISO7231MDWR	ISO7242CDWR
ISO35DWRG4	ISO7221CD	ISO7231MDWRG4	ISO7242MDW
ISO35MDW	ISO7221CDG4	ISO7240ADW	ISO7242MDWG4
ISO35MDWR	ISO7221CDR	ISO7240ADWG4	ISO7242MDWR
ISO721D	ISO7221CDRG4	ISO7240ADWR	ISO7242MDWRG4
ISO721DG4	ISO7221MD	ISO7240ADWRG4	MPD23782D
ISO721DR	ISO7221MDG4	ISO7240CDW	
ISO721DRG4	ISO7221MDR	ISO7240CDWG4	

Qualification Plan

**BCB site change from Amkor K4 to TIEM as well as BOM
change to latest approved ISO BOM
(Qualification Target date: Apr 01, 2018)**

Product Attributes

Attributes	Qual Device: AMC1203BD UB	Qual Device: ISO7221AQD RQ1	Qual Device: ISO7221 CD	Qual Device: ISO7221C HD	Qual Device: AMC1203B DW	Qual Device: ISO3082 DW	Qual Device: ISO35TD W	Qual Device: ISO7241CQDW RQ1
Assembly Site	HNT	TAI	TAI	TAI	TAI	TAI	TAI	TAI
Package Family	SOP	SOIC	SOIC	SOIC	SOIC	SOIC	SOIC	SOIC
Flammabil ity Rating	UL 94 V-0	UL 94 V-0	UL 94 V- 0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V- 0	UL 94 V-0
Wafer Fab Supplier	DFAB, TSMC	DFAB	DFAB	DFAB	DFAB, TSMC	DFAB	DFAB	DFAB
Wafer Fab Process	0.5UM, LBC4	LBC4	LBC4	LBC4	0.5UM, LBC4	LBC3S, LBC4	LBC4, lbc3s	LBC4

- QBS: Qual By Similarity

- Qual Devices ISO7221CHD and ISO7221CD are qualified at LEVEL1-260C

- Qual Devices ISO3082DW and ISO35TDW are qualified at LEVEL2-260C

- Qual Devices ISO7241CQDWRQ1, AMC1203BDUB, AMC1203BDW, and ISO7221AQDRQ1 are qualified at LEVEL3-260C

- The following Devices contain multiple dies: ISO35TDW, ISO7221CHD, ISO7221CD, ISO7241CQDWRQ1, AMC1203BDUB, ISO7221AQDRQ1, AMC1203BDW, ISO3082DW

Qualification Plan

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: ..AMC1203BDUB	Qual Device: .ISO7221AQDRQ1	Qual Device: .ISO7221CD	Qual Device: .ISO7221CHD
AC	Autoclave 121C	96 Hours	3/77/TBD	3/77/TBD	3/77/TBD	1/77/TBD
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	TBD	TBD	TBD
HAST	**Biased HAST 130C/85%RH	96 Hours	3/77/TBD	3/77/TBD	3/77/TBD	-
HTOL	Life Test, 140C	480 Hours	-	3/77/TBD	-	-
HTSL	High Temp. Storage Life, 175C	500 Hours	-	1/45/TBD	-	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	3/77/TBD	-	3/77/TBD	-
TC	Temperature Cycle, - 65/150C	Cycles	3/77/TBD	3/77/TBD	3/77/TBD	-
WBP	Bond Pull	76 Wires, 3 units min	3/76/TBD	3/76/TBD	3/76/TBD	3/76/TBD
WBS	Ball Bond Shear	Wires	3/76/TBD	3/76/TBD	3/76/TBD	3/76/TBD

Type	Test Name / Condition	Duration	Qual Device: AMC1203BDW	Qual Device: ISO3082DW	Qual Device: ISO35TDW	Qual Device: ISO7241CQDWRQ1
AC	Autoclave 121C	96 Hours	1/77/TBD	1/77/TBD	1/77/TBD	3/77/TBD
ED	Electrical Characterization	Per Datasheet Parameters	TBD	TBD	TBD	-
HAST	**Biased HAST 130C/85%RH	96 Hours	-	-	-	3/77/TBD
HTOL	Life Test, 140C	480 Hours	-	-	-	3/77/TBD
HTSL	High Temp. Storage Life, 175C	500 Hours	-	-	-	1/45/TBD
HTSL	High Temp. Storage Bake, 170C	420 Hours	1/77/TBD	1/77/TBD	1/77/TBD	-
TC	Temperature Cycle, - 65/150C	Cycles	1/77/TBD	1/77/TBD	1/77/TBD	3/77/TBD
WBP	Bond Pull	76 Wires, 3 units min	1/76/TBD	1/76/TBD	1/76/TBD	3/76/TBD
WBS	Ball Bond Shear	Wires	1/76/TBD	1/76/TBD	1/76/TBD	3/76/TBD

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com